

Amendment and Response

Applicant: Irwin Aberin et al.

Serial No.: 10/588,927

Filed: August 3, 2007

Docket No.: I431.168.101/FIN581PCT/US

Title: SEMICONDUCTOR PACKAGE WITH PERFORATED SUBSTRATE

IN THE CLAIMS

Please amend claims 17, 22, 24, 30, and 33 as follows:

1-16 (Cancelled)

17. (Currently Amended) A method to assemble a substrate for a semiconductor package comprising:

providing a substrate comprising a sheet of core material and a plurality of upper contact traces and upper contact pads on ~~its~~an upper surface of the substrate, a second plurality of lower conducting traces and external contact areas on ~~its~~a bottom surface of the substrate, and conducting vias connecting the upper conducting traces and lower conducting traces;

forming a plurality of non-plated vent holes through the substrate ~~in~~within a semiconductor chip mounting area defined on the upper surface and in areas of the substrate adjacent to ~~but outside of~~ the semiconductor chip mounting area; and

covering the upper surface of the substrate with a layer of solder resist and the lower surface of the substrate with a layer of solder resist, but leaving the contact areas free from solder resist, wherein the layer of solder resist on the upper surface of the substrate closes one end of the vent holes.

18. (Cancelled)

19. (Previously Presented) The method to assemble a substrate of claim 17, wherein the vent holes include solder resist.

20. (Previously Presented) The method to assemble a substrate of claim 17, wherein the vent holes are formed by drilling.

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21. (Previously Presented) The method to assemble a substrate of claim 17, further comprising forming the vent holes in the core material before forming a plurality of upper contact traces and upper contact pads on its upper surface, a second plurality of lower conducting traces and external contact areas on its bottom surface and depositing conducting vias.

22. (Currently Amended) A method to assemble a semiconductor package comprising:
providing a substrate comprising a sheet of core material and a plurality of upper contact traces and upper contact pads on its upper surface, a second plurality of lower conducting traces and external contact areas on its bottom surface and conducting vias connecting the upper conducting traces and lower conducting traces;

forming a plurality of non-plated vent holes in the substrate;

covering the upper surface of the substrate with a layer of solder resist and the lower surface of the substrate with a layer of solder resist leaving the contact areas free from solder resist, wherein the layer of solder resist on the upper surface of the substrate closes one end of the vent holes;

providing a semiconductor chip comprising an active surface including a plurality of chip contact areas;

mounting the chip on the upper surface of the substrate by microscopic solder balls between the chip contacts and upper contact areas, wherein ~~non-plated vent holes of the plurality of non-plated vent holes are disposed in an area of the substrate below and directly underneath the semiconductor chip and in areas adjacent to but not directly underneath the semiconductor chip;~~

performing a solder reflow; and

~~underfilling the area between the chip and the upper surface of the redistribution board substrate with epoxy resin.~~

23. (Previously Presented) The method of claim 22, including covering the upper surface of the chip and the substrate with a mold material.

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24. (Currently Amended) A substrate for a semiconductor package comprising:
a sheet of core material;
a plurality of upper conducting traces and upper contact pads on an upper surface of the sheet, a second plurality of lower conductive traces and external contact areas on a bottom surface of the sheet and a plurality of conducting vias connecting the upper conducting traces and lower conducting traces;
a plurality of non-plated vent holes through the sheet ~~in~~within a semiconductor chip mounting area defined on the upper surface and in areas of the substrate adjacent to but not outside of the semiconductor chip mounting area; and
a layer of solder resist covering the upper surface of the substrate and a layer of solder resist covering the lower surface of the substrate, but leaving the contact areas free from solder resist, wherein the layer of solder resist covering the upper surface closes an end of the plurality of non-plated vent holes at the upper surface.
25. (Previously Presented) The substrate of claim 24, wherein the vent holes include solder resist.
26. (Cancelled)
27. (Previously Presented) The substrate of claim 24, wherein the plurality of vent holes are laterally located towards the center of the substrate.
28. (Previously Presented) The substrate of claim 24, wherein the plurality of vent holes are laterally located towards the center and towards the outer edges of the substrate.

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29. (Previously Presented) The substrate of claim 24, wherein the vent holes have a diameter of approximately 1 μ m to approximately 5mm or approximately 10 μ m to approximately 0.5mm or approximately 100 μ m.

30. (Currently Amended) A semiconductor package comprising:

a sheet of core material;

a plurality of upper conducting traces and upper contact pads on an upper surface of the sheet, a second plurality of lower conductive traces and external contact areas on a bottom surface of the sheet and a plurality of conducting vias connecting the upper conducting traces and lower conducting traces;

a plurality of non-plated vent holes through the sheet;

a layer of solder resist covering the upper surface of the sheet and a layer of solder resist covering the lower surface of the sheet but leaving the contact areas free from solder resist, wherein the layer of solder resist covering the upper surface closes an end of the vent holes at the upper surface; and

a semiconductor chip including an active surface with a plurality of chip contact areas electrically connected to the sheet, wherein ~~non-plated vent holes of the plurality of non-plated vent holes are disposed in an area of the sheet below directly underneath the semiconductor chip and in areas of the sheet adjacent to but not directly underneath the semiconductor chip.~~

31. (Previously Presented) The semiconductor package of claim 30, wherein the chip is encapsulated by mold material.

32. (Previously Presented) The semiconductor package of claim 30, wherein the chip is mounted to the sheet by a flip-chip technique.

33. (Currently Amended) A substrate for a semiconductor package comprising:

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a sheet of core material with an upper surface and a bottom surface each covered with a layer of solder resist;

 a plurality of upper conducting traces and upper contact pads on the upper surface;

 a plurality of bottom conductive traces and external contact areas on the bottom surface;

 a plurality of conducting vias connecting the upper conducting traces and bottom conducting traces;

 a plurality of non-plated vent holes through the sheet ~~in~~within a chip mounting area defined on the upper surface and in areas adjacent to but outside of the chip mounting area; and

 a layer of solder resist covering the upper surface and a layer of solder resist covering the bottom surface except for the contact areas, wherein the layer of solder resist covering the upper surface closes an end of the vent holes at the upper surface.

34. (Previously Presented) The substrate of claim 33, wherein the vent holes include solder resist.

35. (Cancelled)

36. (Previously Presented) The substrate of claim 33, wherein the plurality of vent holes are laterally located towards the center of the substrate.